AUTOMOTIV

COMPLIANT

HALOGEN FREE

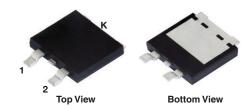


Vishay General Semiconductor

Dual Low-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low $V_F = 0.36 \text{ V}$ at $I_F = 2.5 \text{ A}$

eSMP® Series SMPD (TO-263AC)





LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	2 x 5 A				
V_{RRM}	60 V				
I _{FSM}	100 A				
V_F at $I_F = 5$ A ($T_J = 125$ °C)	0.48 V				
T _J max.	150 °C				
Package	SMPD (TO-263AC)				
Circuit configuration Common cathode					

FEATURES

- Trench MOS Schottky technology
- Very low profile typical height of 1.7 mm
- Ideal for automated placement
- · Low forward voltage drop, low power losses
- · High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

MECHANICAL DATA

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER		SYMBOL	V10DL63C	UNIT	
Device marking code			V10DL63C		
Maximum repetitive peak reverse voltage		V _{RRM}	60	V	
Maximum average forward rectified current (fig. 1)	per device	. (1)	10	^	
	per diode	I _{F(AV)} ⁽¹⁾	5	A	
Peak forward surge current 8.3 ms single half superimposed on rated load per diode	sine-wave	I _{FSM}	100	А	
Operating junction temperature range		T _J ⁽²⁾	-40 to +150	°C	
Storage temperature range		T _{STG}	-55 to +150		

Notes

⁽¹⁾ Mounted on infinite heatsink

⁽²⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta,JA}$



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)							
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT	
Instantaneous forward voltage per diode	I _F = 2.5 A	T _J = 25 °C	$T_{J} = 25 ^{\circ}\text{C}$ $V_{F}^{(1)}$ $V_{F}^{(1)}$	0.45	-	V	
	I _F = 5 A			0.52	0.60		
	I _F = 2.5 A	T _J = 125 °C		0.36	-		
	I _F = 5 A			0.48	0.55		
Reverse current at rated V _R per diode	V _B = 60 V	T _J = 25 °C	I _R ⁽²⁾	-	0.08	mA	
	$V_{R} = 60 \text{ V}$ $T_{J} = 125 \text{ °C}$	IR (=)	4	9	IIIA		
Typical junction capacitance per diode	4.0 V, 1 MHz		CJ	740	-	pF	

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL V10DL63C			
Typical thermal resistance per device	R ₀ JC ⁽¹⁾	2.5	°C/W	
	R _{0JA} (2)(3)	58	C/VV	

Notes

(1) Mounted on infinite heatsink

 $^{(2)} \ \ \, \text{The heat generated must be less than the thermal conductivity from junction-to-ambient:} \ dP_D/dT_J < 1/R_{\theta JA} - \text{junction-to-ambient}$

(3) Free air, without heatsink

ORDERING INFORMATION (Example)						
PREFERRED P/N	PREFERRED P/N UNIT WEIGHT (g) PACKAGE CODE		BASE QUANTITY	DELIVERY MODE		
V10DL63C-M3/I	0.55	1	2000/reel	13" diameter plastic tape and reel		
V10DL63CHM3/I (1)	0.55	I	2000/reel	13" diameter plastic tape and reel		

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

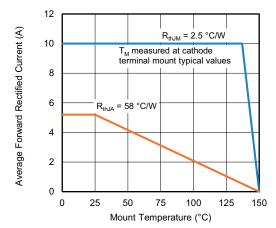
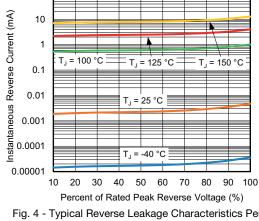


Fig. 1 - Maximum Forward Current Derating Curve



100

Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

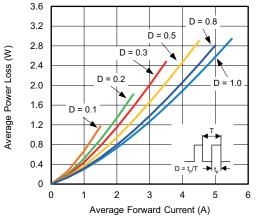


Fig. 2 - Average Power Loss Characteristics Per Diode

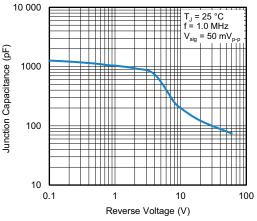


Fig. 5 - Typical Junction Capacitance Per Diode

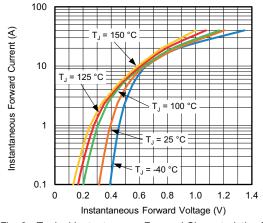


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

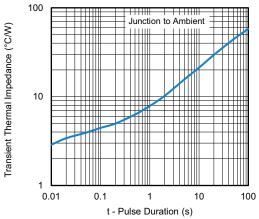


Fig. 6 - Typical Transient Thermal Impedance



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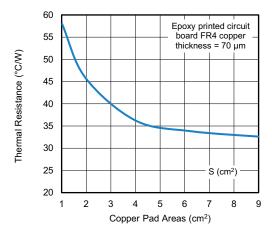
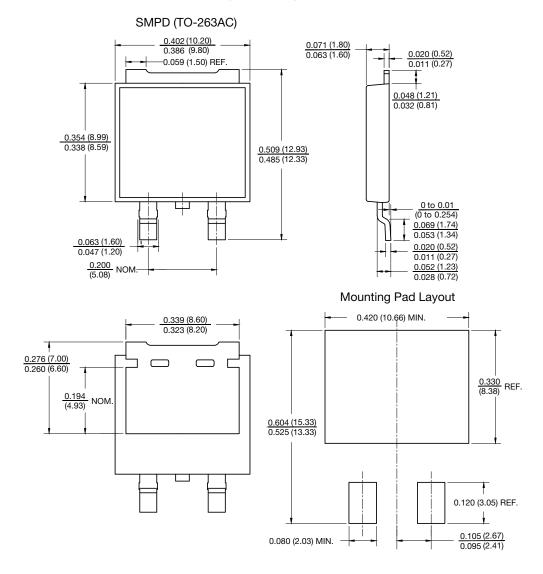


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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